



Material Content Data Sheet



Sales Product Name		6ED003L02-F2		Issued		29. August 2013		
MA#		MA001120094						
Package		PG-TSSOP-28-1		Weight*		107.03 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.034	2.84	2.84	28351	28351
leadframe	non noble metal	nickel	7440-02-0	14.398	13.45		134517	
	non noble metal	iron	7439-89-6	19.882	18.58	32.03	185762	320279
wire	noble metal	gold	7440-57-5	0.846	0.79	0.79	7906	7906
encapsulation	organic material	carbon black	1333-86-4	0.194	0.18		1817	
	plastics	epoxy resin	-	8.231	7.69		76901	
	inorganic material	silicondioxide	60676-86-0	56.385	52.67	60.54	526806	605524
leadfinish	non noble metal	tin	7440-31-5	1.539	1.44	1.44	14383	14383
plating	noble metal	silver	7440-22-4	1.416	1.32	1.32	13226	13226
glue	plastics	acrylic resin	-	0.221	0.21		2066	
	noble metal	silver	7440-22-4	0.885	0.83	1.04	8265	10331
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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